ON Semiconductor®

Update Notification

Document # : FPCN21107ZAB1
Issue Date: 6 June 2017

Title of Change:	Update to FPCN21107ZAB - Assembly & Test site transfer of DPAK products currently manufactured in ON Semiconductor Malaysia facility (SBN) to ON Semiconductor Vietnam (OSV) facility.
Proposed Changed Material First Ship Date:	1 November 2017 (OSV parts available for earlier conversions)
Current Material Last Order Date:	1 November 2017 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	31 December 2017 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.
Product Category:	*Active components – Discrete components*
Contact information	Contact your local ON Semiconductor Sales Office or <Phuong.Hoang@onsemi.com>
Samples	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.
Sample Availability Date:	Samples Available On Request
PPAP Availability Date:	PPAP Available On Request
Additional Reliability Data	Contact your local ON Semiconductor Sales Office or <cheanching.sim@onsemi.com >.
Type of Notification	This is an update to a Final Product/Process Change Notification (FPCN) sent to customers. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.

Change Category	**Type of Change**
Process – Assembly	Move of all or part of assembly to a different location/site/subcontractor.
Process – Assembly	Change of product marking
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.

Description and Purpose:

This Update Notification (UN) is issued to communicate the transfer of Assembly and Test of DPAK products from ON Semiconductor Malaysia (SBN) to ON Semiconductor Vietnam (OSV) in order to ensure support for joint growth and alleviate SBN manufacturing capacity constraints.

The OSV produced devices will utilize the same BOM, Equipment, and Processes. No change to the SBN affected device list of the original FPCN. No change to the request for qualification of the Assembly & Test processes at the ON Semiconductor Vietnam facility announced in FPCN21107ZAB utilizing the OSV specific part numbers. Changing only Assy/Test location and device marking to facilitate site tracking and control.

The OSV part numbers, identified in FPCN21107ZAB, are available to early adaptors for immediate SBN demand conversion. You can view a list of those OSV part numbers, cross referenced to the affected SBN part numbers listed in this Update notification, in the attached Excel file.

Upon completion of this transfer, DPAK demand will be sourced solely from OSV and will no longer be available from SBN. At that time, either the transferring SBN or the current OSV part numbers can be utilized to order these products from OSV.

Reason / Motivation for Change:	• Change benefits for customer(s): o Unconstrained Automotive Sourcing; Mfg floor space for future expansion o Sustained TS16949 Certification with the Same BOM / Equipment / Processes o Allow for increased support for Seremban packages that are currently constrained o OSV has been audited to VDA6.3 • Risks for delayed conversion: o No Seremban supply after Dec 31, 2017 o Limited ability to support bridge build availability.
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	No anticipated impacts. The device(s) has been qualified and validated based on the same Product Specification. The device(s) has successfully passed the AEC-Q101 qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.

Sites Affected:

☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : *ON Seremban, Malaysia* *ON Dong Nai Province, Vietnam* ☐ External Foundry/Subcon site(s)

Marking of Parts/ Traceability of Change:	Product from ON Semiconductor Vietnam (OSV) will be marked with site code “VN” prior to the date code while the Seremban device will not reflect a site code marking.

Reliability Data Summary:

No Changes. Successfully Passed AEC-Q101 Qualification. Please refer to original FPCN

Electrical Characteristic Summary:

No Changes. Electrical characteristics are not impacted. Please refer to original FPCN

List of affected Standard Parts:

Transferring Malaysia (SBN) Part Number	Qualification Vehicle
NRVBD650CTG	MBRD5H100T4G
NRVBD660CTRLG	
SBRD8320T4G	
SBRD8330G	
SBRD8330T4G	
SBRD8340G	
SBRD8350G	
SBRD8350T4G	
SBRD8340T4G	
NRVBD640CTG	
NRVBD650CTT4G	
NRVBD660CTG	
SBR835LT4G	
SBRD81035CTLG	
SBRD8320G	
SBRD8360G	
SBRD8360RLG	
SBRD8835LG	
SSRD8620CTRG	
NRVUD320W1T4G	MURHD560T4G
NRVUD340T4G	
SUR620CTT4G	
SURHD8560T4G	
SURD8530T4G	
NRVUD550PFT4G	
NRVUD620CTG	
STD110N02RT4G	NTD110N02RT4G
NVD3055-094T4G	NTD6414ANT4G
NVD3055L170T4G	
NVD6414ANT4G	
NVD6415ANT4G	
NVD6416ANLT4G-001	
NVD6416ANT4G	
NVD6495NLT4G	

Transferring Malaysia (SBN) Part Number	Qualification Vehicle
NJVMJD42CT4G	MJD340T4G
SJD127T4G	MJD350T4G

List of affected Customer Specific Parts:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert.